

Appln. No. 09/554,629
Supplementary Amendment dated September 8, 2003
Reply to Office Action of March 3, 2003

Amendments to the Claims are reflected in the listing of claims
which begins on page 2 of this paper.

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Amendments to the Claims:

Please amend claim 2 as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Previously Presented). A wafer holding device for use in an apparatus for treating a principal surface of a semiconductor wafer under a predetermined heating condition while the back surface of said principal surface of the wafer is held by the device at a predetermined position within a chamber of said apparatus, said device comprising:

a susceptor formed in the surface thereof with a wafer loading area for supporting the back surface of the wafer,

a plurality of support pins each arranged at one of four equiangularly spaced positions along a circumference of at least one concentric circle in said wafer loading area so as to protrude from the surface of said susceptor, and

a resilient mechanism made from quartz for supporting said support pins.

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Claim 2 (Currently Amended). The wafer holding device according to claim 1, wherein said support pins are disposed in position which support the wafer along the crystal orientation (110) with respect to the crystal plane (100) of the wafer.

Claim 3 (Previously Presented). The wafer holding device according to claim 1, wherein said resilient mechanism includes a plurality of flexible members made from quartz each supporting one of said support pins.

Claim 4 (Previously Presented). A wafer holding device adapted for use in an apparatus for treating a principal surface of a semiconductor wafer under a predetermined heating condition while the back surface of said principal surface of the wafer is held by the device at a predetermined position within a chamber of said apparatus, said device comprising:

a susceptor formed in the surface thereof with a wafer loading area of supporting the back surface of the wafer, and
a plurality of support pins each arranged at one of four equiangularly spaced positions along a circumference of at least one concentric circle in said wafer loading area so as to protrude from the surface of said susceptor, each of said support

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pins including a resilient mechanism, wherein said resilient mechanism includes a plurality of flexible members each supporting one of said support pins,

wherein each said flexible member comprises a leaf spring made from quartz.

Claims 5-8 (Cancelled).